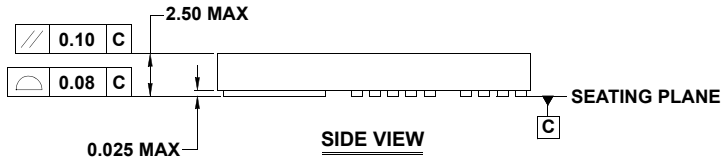
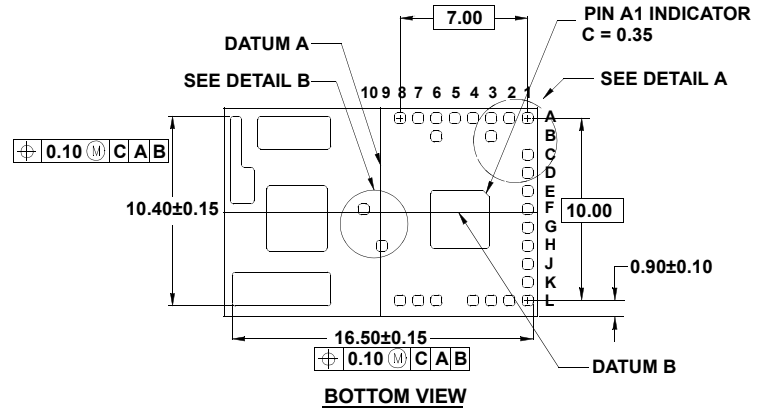
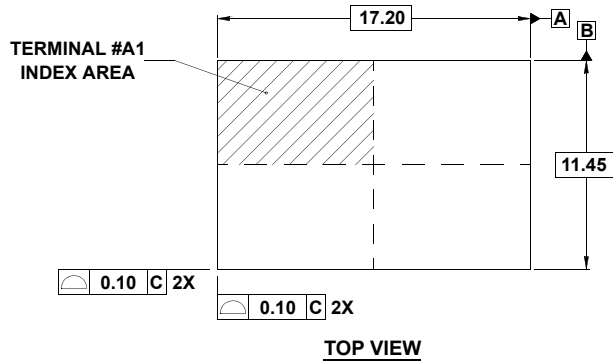


Package Outline Drawing

Y32.17.2x11.45

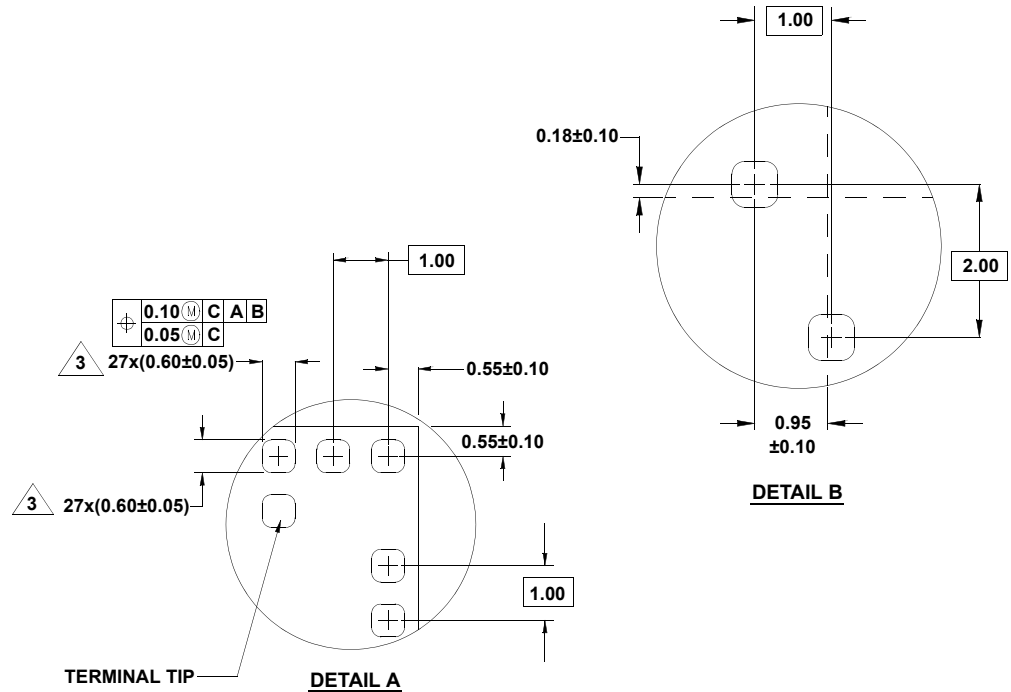
32 I/O 17.2mm x 11.45mm x 2.5mm HDA MODULE

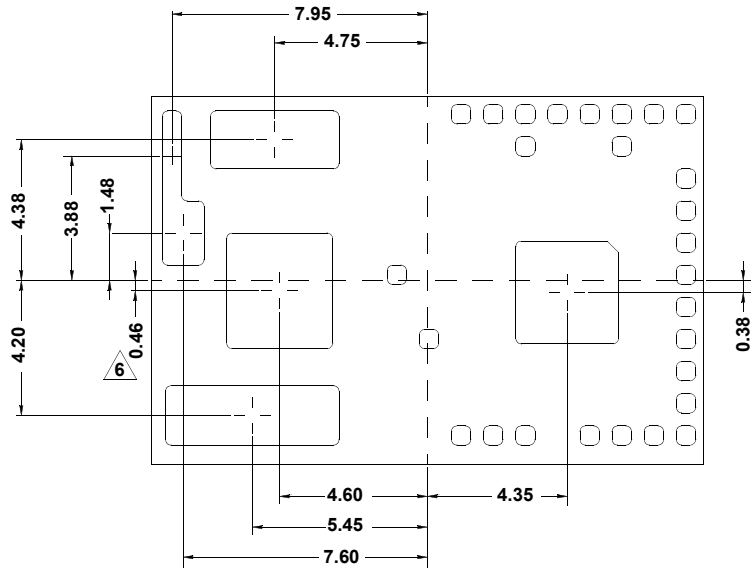
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NOTES:

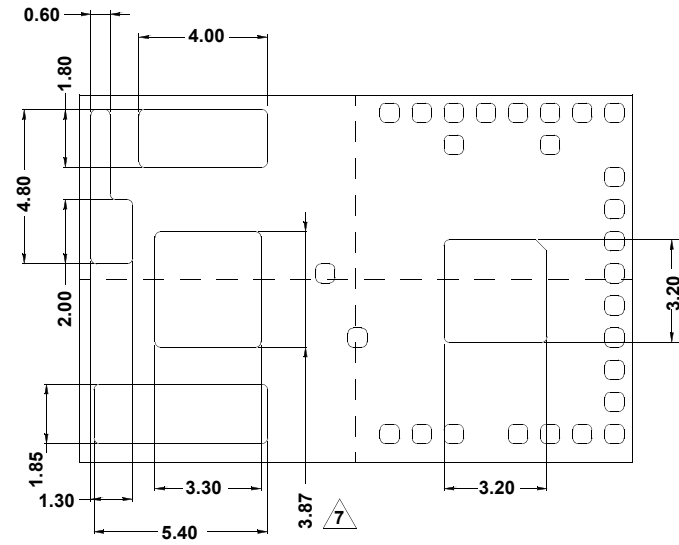
1. All dimensions are in millimeters.
2. 1.0mmx1.0mm represents the basic land grid pitch.
3. "27" is the total number of I/O (excluding large pads). All 27 I/O's are centered in a fixed row and column matrix at 1.0mm pitch BSC.
4. Dimensioning and tolerancing per ASME Y14.5M-1994.
5. Tolerance for exposed DAP edge location dimension on page 2 is ±0.1mm.





CENTERLINE POSITION DETAILS FOR THE 5 EXPOSED DAPS

BOTTOM VIEW

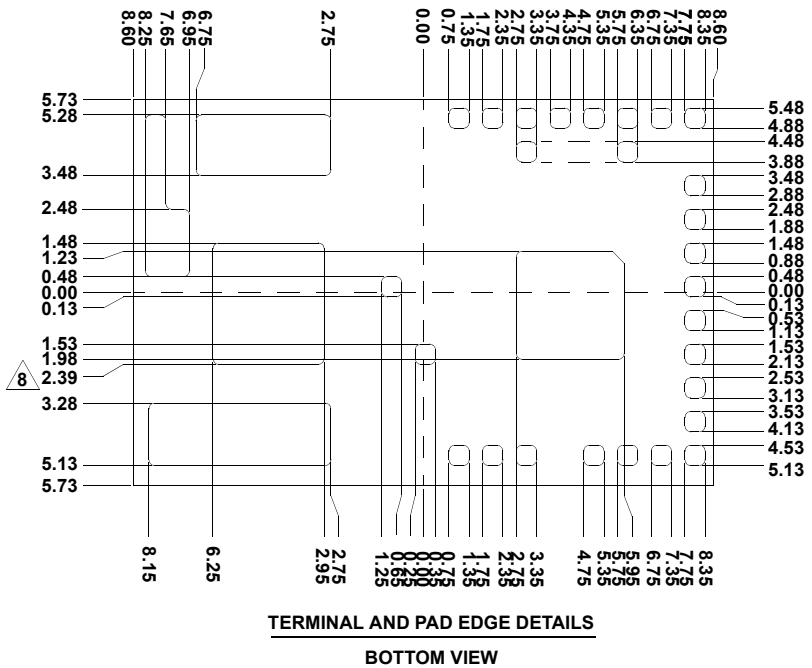


SIZE DETAILS FOR THE 5 EXPOSED DAPS

BOTTOM VIEW

NOTES:

- 6. Shown centerline measurement of 0.46mm applies to ZL9006M module. For the ZL9010M module, this measurement is 0.33mm. All other measures identical for both the ZL9006M and ZL9010M modules.
- 7. Shown pad edge measurement of 3.87mm applies to ZL9006M module. For the ZL9010M module, this measurement is 3.60mm. All other measurements are identical for both the ZL9006M and ZL9010M modules.



NOTES:

8. Shown edge pad measurement of 2.39mm applies to ZL9006M module. For the ZL9010M module, this measurement is 2.13mm. All other measurements are identical for both the ZL9006M & ZL9010M modules.

